

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Zener Diode

DZ2J100×0L

Panasonic

DZ2J100×0L

Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

■ Features

- · Excellent rising characteristics of zener current Iz
- · Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: NJ or NU

■ Packaging

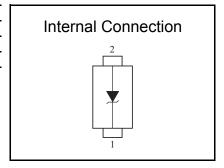
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	200	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1 Mounted on glass epoxy print board ($45 \text{ mm} \times 45 \text{ mm} \times 1 \text{ mm}$) Solder in (Recommended land pattern)

*2 Test method : IEC61000_4_2 (C = 150 pF, R = 330 Ω , Contact discharge : 10 times)



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	9.50		10.50	V
Zener operating resistance	RZ	IZ = 5 mA			30	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			60	Ω
Reverse current	IR	VR = 7 V			0.05	μΑ
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		7.2		mV/°C

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 - 2. Absolute frequency of input and output is 5 MHz.
 - 3. *1 The temperature must be controlled 25 °C for VZ mesurement. VZ value measured at other temperature must be adjusted to VZ (25 °C).
 - *2 VZ guaranted 20 ms after current flow

*3 Tj = 25 °C to 150 °C

Rank classification

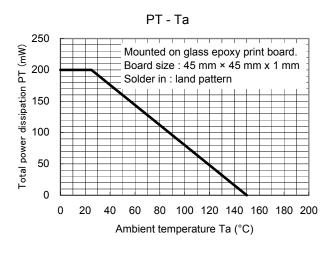
Code	M	0				
Rank	M	No-rank				
VZ	9.75 to 10.25	9.50 to 10.50				
Marking symbol	NU	NJ				

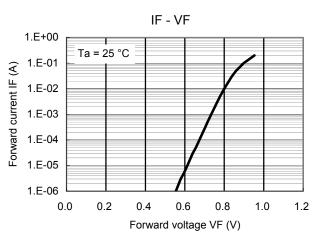
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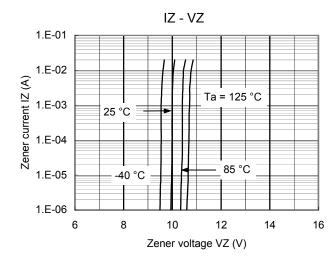
Zener Diode

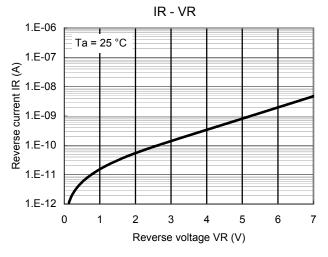
DZ2J100×0L

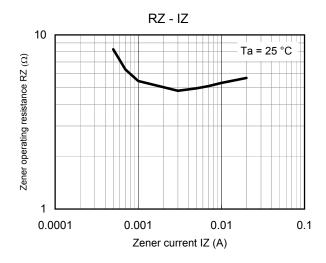
Technical Data (reference)

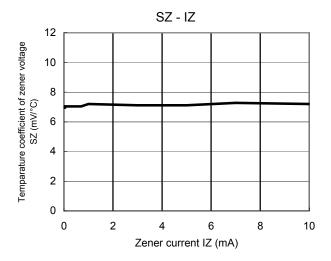










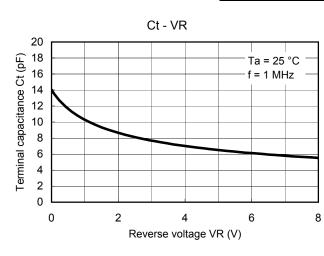


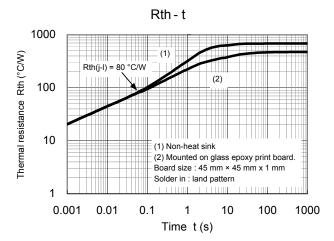
Panasonic

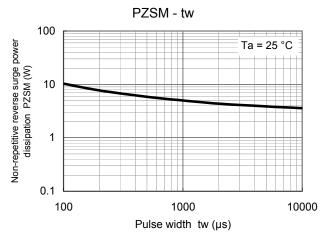
Zener Diode

DZ2J100×0L

Technical Data (reference)







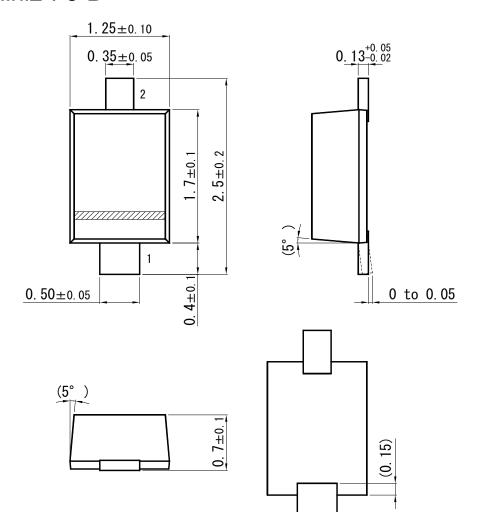
Panasonic

Zener Diode

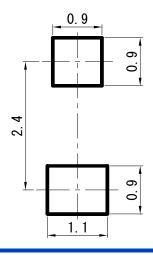
DZ2J100×0L

SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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